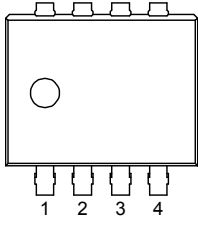
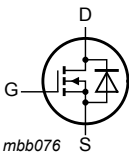


## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 LPAK33 (SOT1210)	 mbb076
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN020-30MLC	LPAK33	Plastic single ended surface mounted package (LPAK33); 4 leads	SOT1210

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25\text{ °C}$	-	30	V
$V_{GS}$	gate-source voltage		-20	20	V
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{mb} = 25\text{ °C}; \text{Fig. 1}$	-	31.8	A
		$V_{GS} = 10\text{ V}; T_{mb} = 100\text{ °C}; \text{Fig. 1}$	-	22.5	A
$I_{DM}$	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ °C}; \text{Fig. 4}$	-	127	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}; \text{Fig. 2}$	-	33	W
$T_{stg}$	storage temperature		-55	175	°C
$T_j$	junction temperature		-55	175	°C
$T_{sld(M)}$	peak soldering temperature		-	260	°C
$V_{ESD}$	electrostatic discharge voltage	MM (JEDEC JESD22-A115)	130	-	V
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25\text{ °C}$	-	27.4	A
$I_{SM}$	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ °C}$	-	127	A

Symbol	Parameter	Conditions	Min	Max	Unit
Avalanche ruggedness					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10\text{ V}$ ; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $I_D = 31\text{ A}$ ; $V_{sup} \leq 30\text{ V}$ ; $R_{GS} = 50\text{ }\Omega$ ; unclamped; <a href="#">Fig. 3</a>	-	7.7	mJ

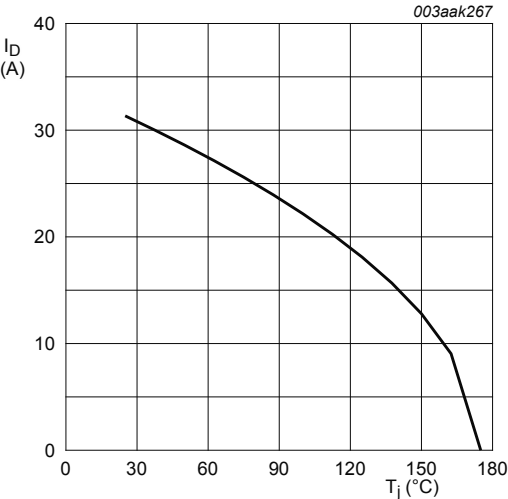


Fig. 1. Continuous drain current as a function of mounting base temperature

$$V_{GS} \geq 10V$$

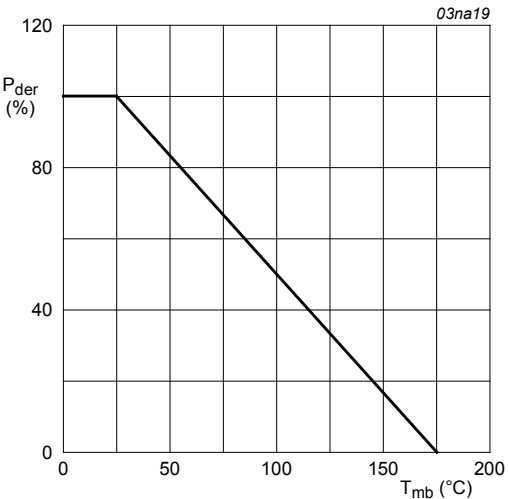


Fig. 2. Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

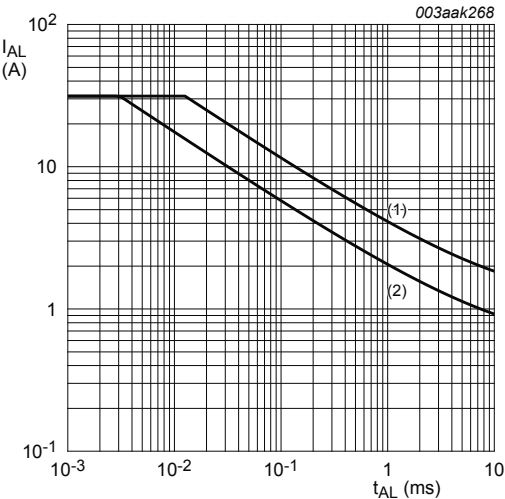


Fig. 3. Single pulse avalanche rating; avalanche current as a function of avalanche time

$$(1) T_{j(\text{init})} = 25^{\circ}\text{C}; (2) T_{j(\text{init})} = 100^{\circ}\text{C}$$

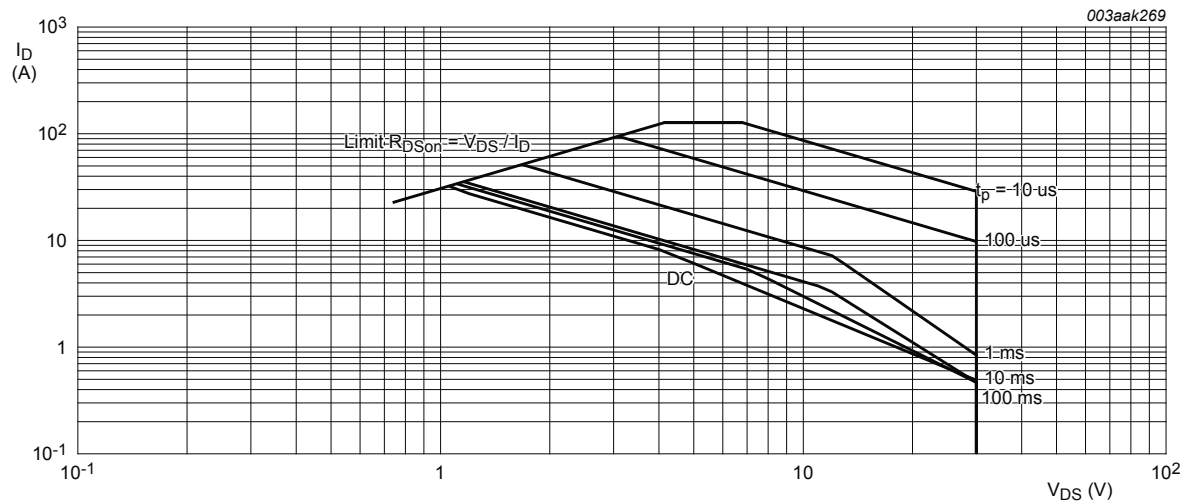


Fig. 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{mb} = 25^{\circ}C$ ;  $I_{DM}$  is a single pulse

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	4.32	4.56	K/W

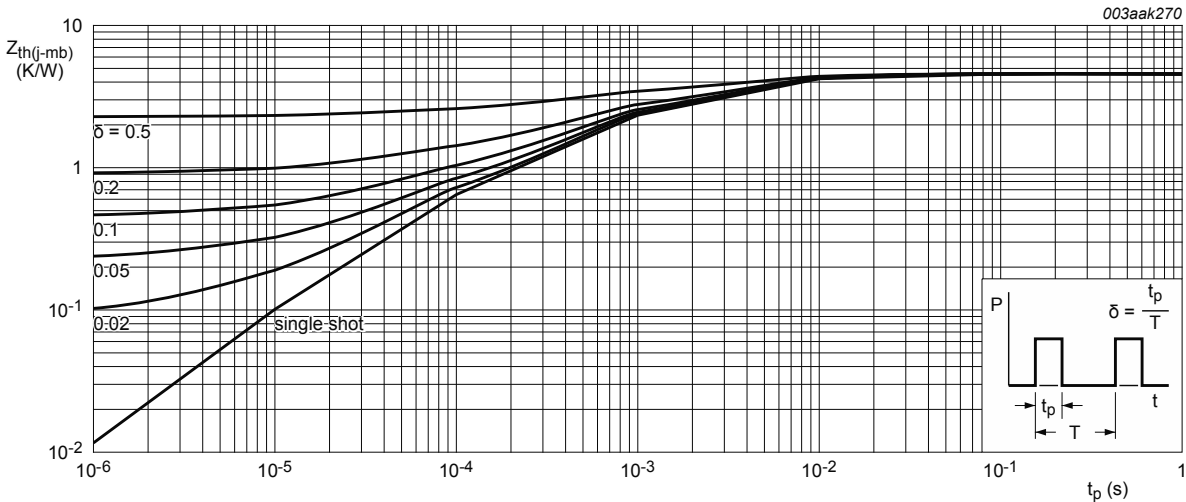


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 13.5\text{ A}$ ; $V_{GS} = 0\text{ V}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; $t_p \leq 50\text{ }\mu\text{s}$	34	-	-	V
		$I_D = 250\text{ }\mu\text{A}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = 25\text{ °C}$	30	-	-	V
		$I_D = 250\text{ }\mu\text{A}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = -55\text{ °C}$	27	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\text{ mA}$ ; $V_{DS} = V_{GS}$ ; $T_j = 25\text{ °C}$	1.05	1.62	1.95	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature		-	-3.5	-	mV/K
$I_{DSS}$	drain leakage current	$V_{DS} = 30\text{ V}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = 25\text{ °C}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 30\text{ V}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = 150\text{ °C}$	-	-	100	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 16\text{ V}$ ; $V_{DS} = 0\text{ V}$ ; $T_j = 25\text{ °C}$	-	-	100	nA
		$V_{GS} = -16\text{ V}$ ; $V_{DS} = 0\text{ V}$ ; $T_j = 25\text{ °C}$	-	-	100	nA
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}$ ; $I_D = 5\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 10</a>	-	20.5	27	mΩ
		$V_{GS} = 4.5\text{ V}$ ; $I_D = 5\text{ A}$ ; $T_j = 150\text{ °C}$ ; <a href="#">Fig. 10</a> ; <a href="#">Fig. 11</a>	-	-	43.2	mΩ
		$V_{GS} = 10\text{ V}$ ; $I_D = 5\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 10</a>	-	14.7	18.1	mΩ
		$V_{GS} = 10\text{ V}$ ; $I_D = 5\text{ A}$ ; $T_j = 150\text{ °C}$ ; <a href="#">Fig. 10</a> ; <a href="#">Fig. 11</a>	-	-	29	mΩ
$R_G$	gate resistance	$f = 1\text{ MHz}$	0.68	1.37	2.74	Ω
<b>Dynamic characteristics</b>						
$Q_{G(\text{tot})}$	total gate charge	$I_D = 5\text{ A}$ ; $V_{DS} = 15\text{ V}$ ; $V_{GS} = 10\text{ V}$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>	-	9.5	-	nC
		$I_D = 5\text{ A}$ ; $V_{DS} = 15\text{ V}$ ; $V_{GS} = 4.5\text{ V}$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>	-	4.6	-	nC
		$I_D = 0\text{ A}$ ; $V_{DS} = 0\text{ V}$ ; $V_{GS} = 10\text{ V}$	-	8.4	-	nC
$Q_{GS}$	gate-source charge	$I_D = 5\text{ A}$ ; $V_{DS} = 15\text{ V}$ ; $V_{GS} = 4.5\text{ V}$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>	-	1	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	0.3	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	0.7	-	nC
$Q_{GD}$	gate-drain charge		-	1.7	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 5\text{ A}$ ; $V_{DS} = 15\text{ V}$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>	-	2.4	-	V

N-channel 30 V 18.1 mΩ logic level MOSFET in LPAK33 using TrenchMOS Technology

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 0 V; f = 1 MHz; T <sub>j</sub> = 25 °C; <a href="#">Fig. 14</a>		-	430	-	pF
C <sub>oss</sub>	output capacitance			-	120	-	pF
C <sub>rss</sub>	reverse transfer capacitance			-	70	-	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = 15 V; R <sub>L</sub> = 3 Ω; V <sub>GS</sub> = 4.5 V; R <sub>G(ext)</sub> = 5 Ω		-	6.1	-	ns
t <sub>r</sub>	rise time			-	7.2	-	ns
t <sub>d(off)</sub>	turn-off delay time			-	10.1	-	ns
t <sub>f</sub>	fall time			-	5.1	-	ns
Q <sub>oss</sub>	output charge	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 15 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	2.3	-	nC
Source-drain diode							
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = 5 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 15</a>		-	0.89	1.1	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = 5 A; dI <sub>S</sub> /dt = -100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 15 V		-	13.5	-	ns
Q <sub>r</sub>	recovered charge			-	5.1	-	nC
t <sub>a</sub>	reverse recovery rise time	V <sub>GS</sub> = 0 V; I <sub>S</sub> = 5 A; dI <sub>S</sub> /dt = -100 A/μs; V <sub>DS</sub> = 15 V; <a href="#">Fig. 16</a>		-	6.3	-	ns
t <sub>b</sub>	reverse recovery fall time			-	7.2	-	ns

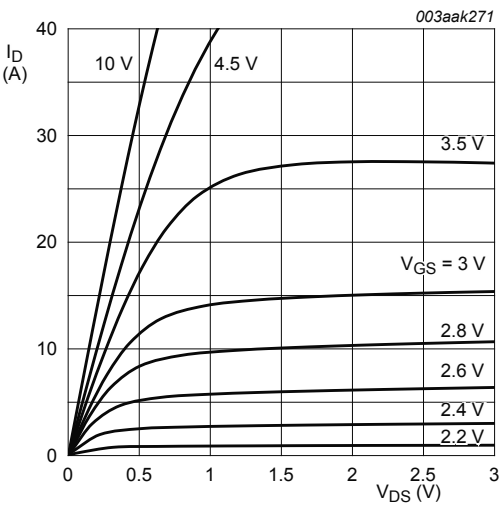


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

$T_j = 25^{\circ}\text{C}$

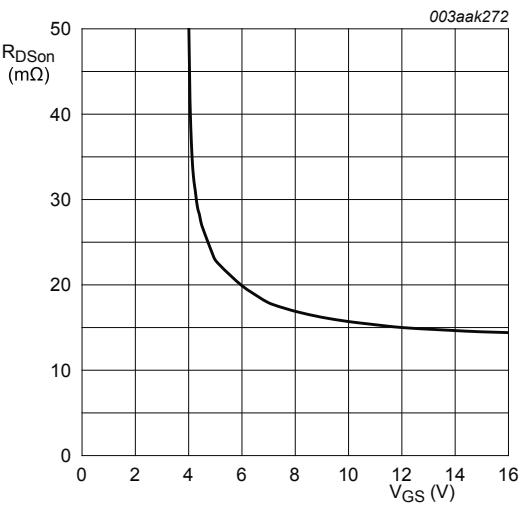


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

$T_j = 25^{\circ}\text{C}; I_D = 10\text{ A}$

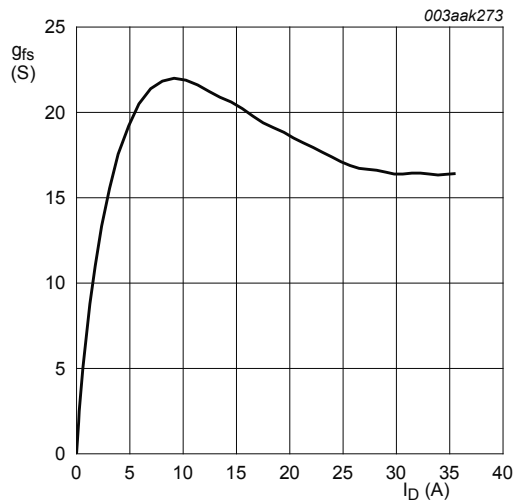


Fig. 8. Forward transconductance as a function of drain current; typical values

$T_j = 25^{\circ}\text{C}; V_{DS} = 10\text{V}$

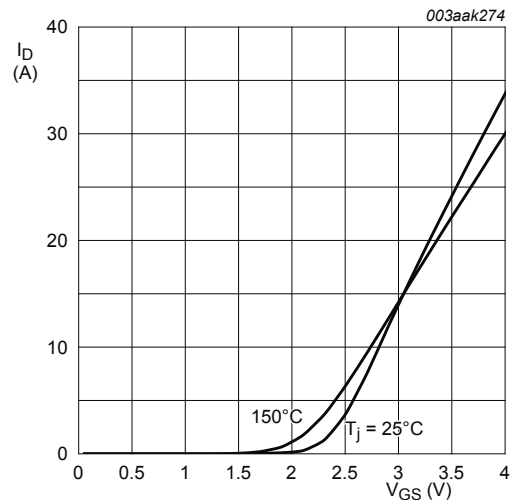


Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

$V_{DS} = 10\text{V}$

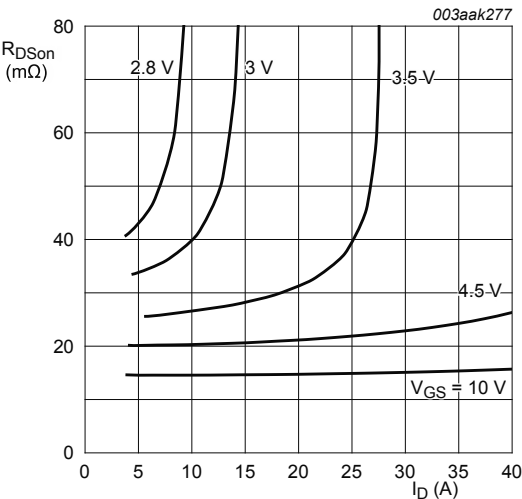


Fig. 10. Drain-source on-state resistance as a function of drain current; typical values

$T_j = 25^{\circ}\text{C}$

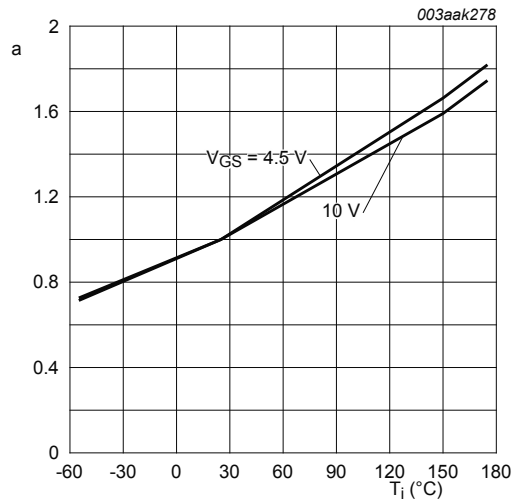


Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon}(25^{\circ}\text{C})}$$

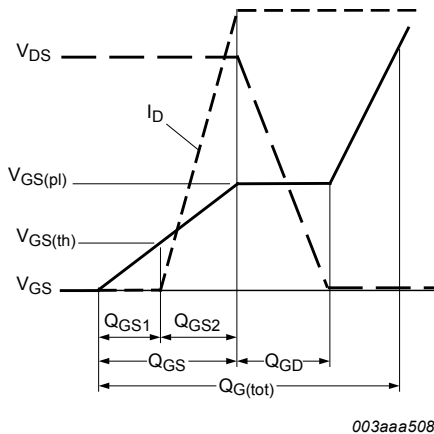


Fig. 12. Gate charge waveform definitions

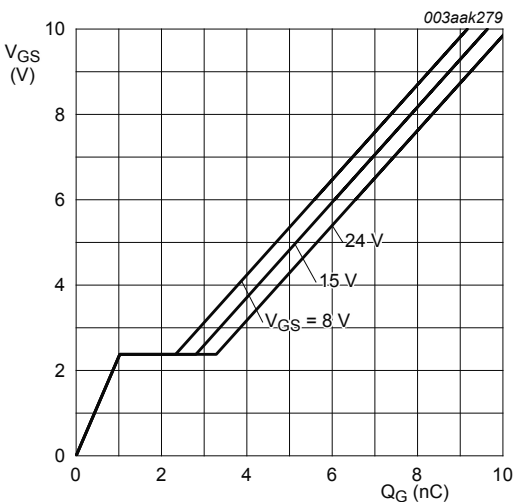


Fig. 13. Gate-source voltage as a function of gate charge; typical values

$T_j = 25^{\circ}C; I_D = 10A$

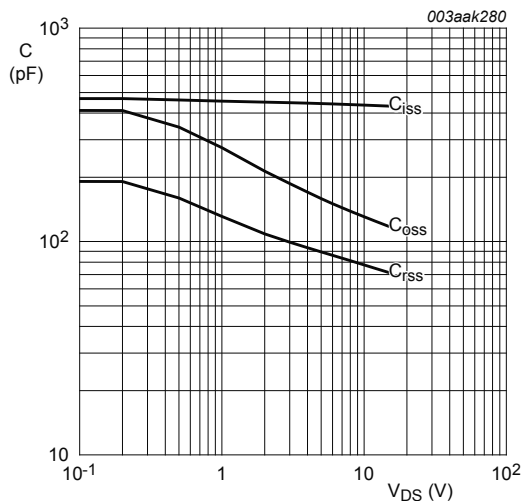


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0V; f = 1MHz$

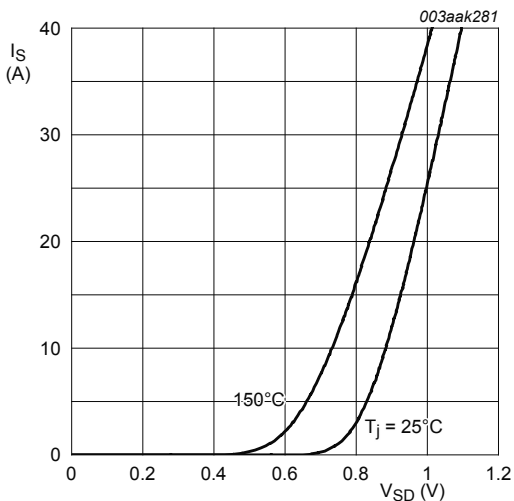


Fig. 15. Source current as a function of source-drain voltage; typical values

$V_{GS} = 0V$

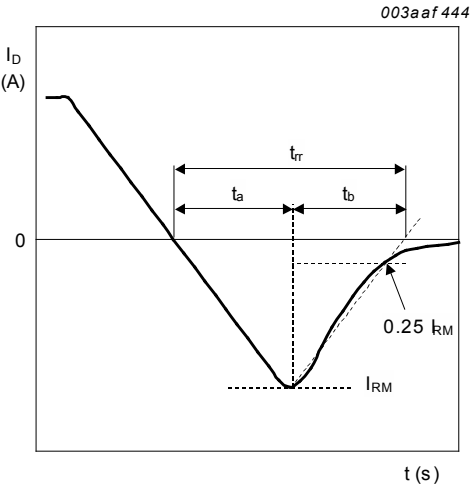


Fig. 16. Reverse recovery timing definition



7. Package outline

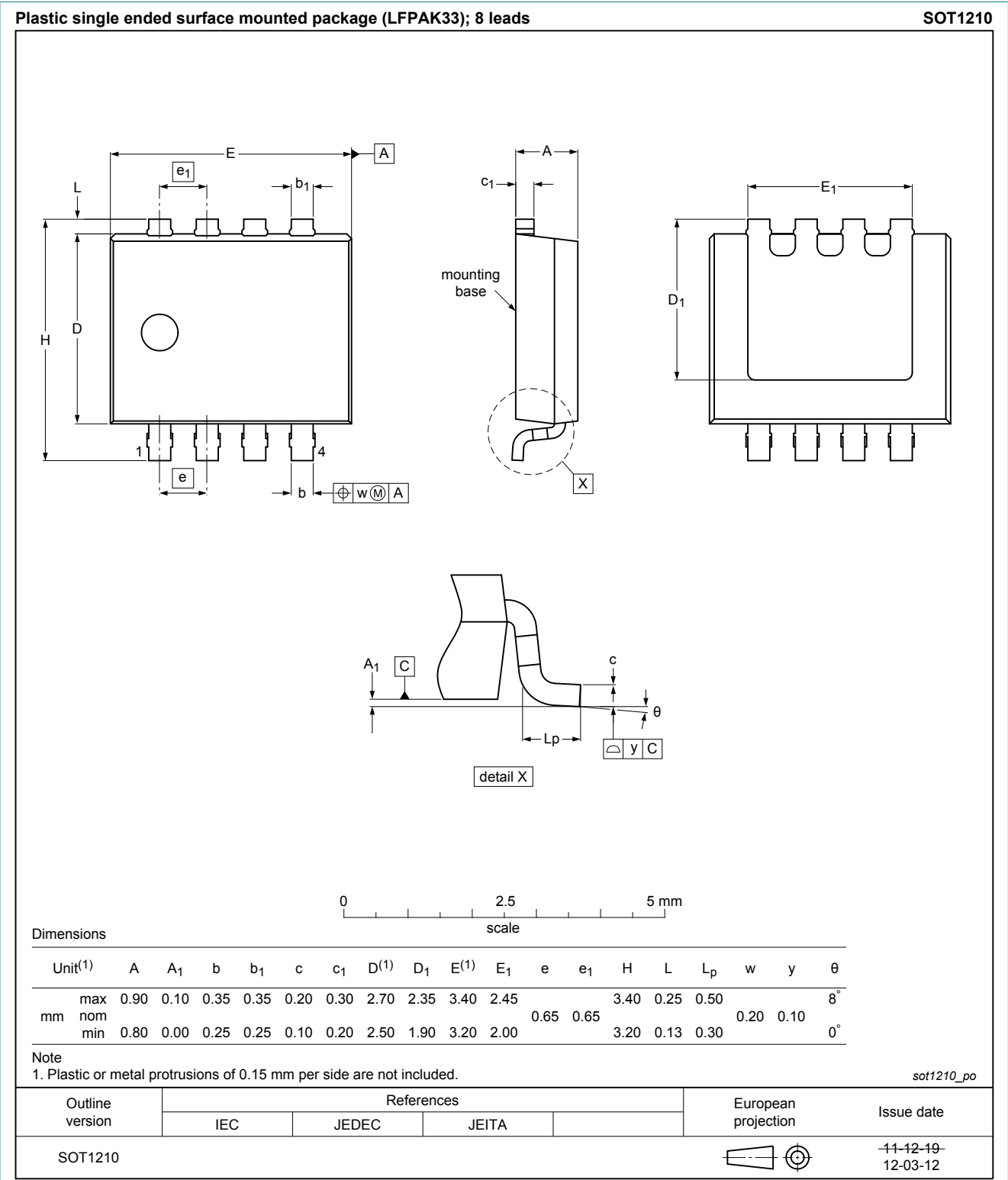


Fig. 17. Package outline LPAK33 (SOT1210)

## 8. Legal information

### 8.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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